



MLCAD 2024 Call for Papers

ACM/IEEE International Symposium on Machine Learning for CAD
September 09-11, 2024
Snowbird, Utah!

MLCAD Symposium

The symposium focuses on Machine Learning (ML) for all aspects of CAD and electronic system design. The symposium is sponsored by both the ACM Special Interest Group on Design Automation (SIGDA) and the IEEE Council on Electronic Design Automation (CEDA). The symposium program will have keynote and invited speakers in addition to technical presentations. MLCAD 2024 will be held physically in Snowbird, Utah, starting with a welcome reception in the evening on September 8, 2024.

Paper Submission:

May 18, 2024

Notification:

July 06, 2024

Camera Ready Version:

July 31, 2024

Website:

<https://mlcad.org/>

Papers should cover one or more aspects of applying ML to enhance CAD of electronic chips and systems. Such aspects include, but are not limited to algorithms, tools, example applications, benchmarking, and innovative solutions like Large Language Models for CAD (LLM-CAD)

Paper Submission

Submissions should be full-length papers of up to six pages (PDF format, double-column, US letter size, using the IEEE format). Submissions must be anonymous to allow a double-blind review process. Submitted papers must describe original work that has not been published/accepted or is currently under review.

Symposium Proceedings

Formal shared ACM/IEEE proceedings will be published containing all accepted papers. Accepted papers will be available in both IEEE Xplore Digital Library and ACM Digital Library.

ACM and IEEE policies

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